EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	("6572780").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/21 08:22
L2	42	chip and film near carrier near film and insulating adj substrate and capacitor and insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/21 08:33
L3	0	2 and sprocket	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/21 08:34
L4	7488	sprocket near hole	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/21 08:34
L5	1	4 and chip and film near carrier near film and insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/21 08:35
L6	39	4 and chip and film near carrier near film and insulating	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/21 08:35
L7	21	6 and wiring adj pattern	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/21 08:35
L8	2	7 and dummy adj wiring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/21 08:36
L9	5	"6900989"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/21 08:38

L10	2	("6900989").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/21 08:38
L11	16	(("6,900,989") or ("7,225,919") or ("7,198,989") or ("7,173,322") or ("6,280,851") or ("6,911,729") or ("6,572,780") or ("6,458,234")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/21 08:39
L12	2	("6,572,780").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/21 08:45
L14	2	("6441474").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/21 08:53
L15	2	("6280851").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/21 08:54
L16	2	("6320135").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/21 10:45
L17	2	("6900989").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/21 10:49
L18	5	("6280851" | "6441474").PN. OR ("6900989").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/04/21 10:51
L19	8	("6280851" | "6458234" | "6572780" | "6900989" | "6911729" | "7173322" | "7198989" | "7225919").PN. OR ("7382042").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/04/21 10:52
L20	4	"6900989"	US-PGPUB; USPAT; USOCR	OR	ON	2009/04/21 10:54
L21	2	("6900989").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/21 10:54
L22	5	("6280851" | "6441474").PN. OR ("6900989").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/04/21 10:56

L23	8	("6280851" | "6458234" | "6572780" | "6900989" | "6911729" | "7173322" | "7198989" | "7225919").PN. OR ("7382042").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/04/21 10:57
L24	2	"US 20060054349"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2009/04/21 11:01
L26	7	"COF film carrier tape"	USPAT	OR	ON	2009/04/21 11:03
L27	4	"COF film carrier tape" and dummy near wiring	USPAT	OR	ON	2009/04/21 11:04
L28	12	"6320135"	USPAT	OR	ON	2009/04/21 11:07
L29	2	("6320135").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/21 11:07
L30	2	("6262473").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/21 11:18
L31	2	("6320135").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/21 11:19
L32	942	174/254.ccls.	USPAT	OR	ON	2009/04/21 14:11
S2	2546	housing with gap and shielding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:00
S6	58	S2 and burst	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:02
S7	31	S2 and burst and ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:02
S8	42	S2 and TVS	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:02

S9	4	S7 and S8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:02
S10	2386	ELECTRONIC adj DEVICE and ESD	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:04
S11	3	S10 and burst same TVS	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:05
S12	776762	electronic adj device and joint or layer and circuit adj board and IC or integrated adj circuit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:41
S13	22312	S12 and ground and housing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:43
S14	3108	S13 and shielding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:43
S15	88	S14 and 361/818.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:43
S16	11	S15 and capacitor and ESD	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:44
S17	2386	electronic adj device and ESD and electronic adj device	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 16:51
S20	772	361/88.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 17:06
S21	1991	361/818.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 17:06

S22	1	S21 and housing adj seam and IC	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 17:07
S28	66	S21 and housing and IC	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/07 17:09
S30	85511	housing and gap and shielding adj unitground burst	USPAT	OR	ON	2008/04/07 17:53
S31	2	housing and gap and shielding adj unit and ground and burst	USPAT	OR	ON	2008/04/07 17:53
S32	13	("3073916" | "3670299" | "4115667" | "4187502").PN. OR ("5012457").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/07 17:54
S33	154	shield$4 same esd same (printed pcb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 10:20
S34	92	S33 same ground$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 10:20
S35	21	S34 same (opening aperture hole window)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 10:22
S36	33	S33 same (opening aperture hole window)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 10:23
S37	21	S36 and S35	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 10:24
S38	1052	361/212.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 10:29
S40	3	S33 and S38	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 10:30

S41	29	S34 same (opening aperture hole window gap)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 13:27
S42	2	"20060023387"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 13:36
S43	2	"20060012969"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 13:38
S44	5086	antiFuse	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 14:24
S48	2	"20060172573"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 16:36
S51	9	notebook and housing and ESd and filter and shielding and ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 16:45
S52	1919339	electronic adj device and ESD and housing and gap and shielding and component filter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 16:55
S53	39	electronic adj device and ESD and housing and gap and shielding and component and filter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 16:55
S55	13877	housing and gap and shielding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 17:17
S56	5196	S55 and ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 17:17
S57	5196	S56 and shielding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 17:18

S58	228	S57 and TVS	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 17:19
S59	33	(shield$4 same esd same (printed pcb) same (opening aperture hole window))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 17:40
S60	558764	"33" and filter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 17:40
S61	1	S59 and filter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/08 17:40
S62	17	"4801273"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/09 10:37
S63	2	("4801273").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/09 10:37
S64	1002418	nootbook and housing and ESd and filter and shielding and ground and gap window	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/09 13:36
S65	2388	ELECTRONIC adj DEVICE and ESD	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/09 14:34
S66	41	S65 and PDA and notebook and mobile adj phone	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/09 14:39
S67	2	"20020048156"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/09 19:08
S69	2	"20050009381"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/09 19:15

S70	3	2004/0183209	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 09:18
S72	2	("20040183209").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/10 09:18
S74	17	built near in near capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 09:26
S76	13	built near in near capacitor and power	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 09:26
S77	9	S76 and pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 09:34
S78	9	S77 and power	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 09:36
S79	697	APPARATUS and INTERCONNECTING and BALL adj GRID adj ARRAY and PRINTED adj CIRCUIT adj BOARD	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 09:55
S80	0	S79 and power adj bar	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 09:57
S81	82	S79 and bar	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 09:57
S82	11	S81 and power adj supply	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 09:57
S83	1543	361/816.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 13:58

S84	669	361/800.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:04
S85	875	361/803.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:04
S86	9	S83 and S84 and S85	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:04
S87	199405	@ad<="20040415" and ("PCB" or "printed circuit board") with shield and ground adj layer and electromagnetic adj radiation and via metal adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:11
S88	2068	S87 and polymer adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:13
S90	29	S88 and flange and ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:13
S91	486	174/377.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:16
S92	4	S88 and S91	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:16
S93	2225371	S90 and mechanical adj connector and ground adj plane and via or window or aperture	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:18
S94	7	S90 and mechanical adj connector and ground adj plane and via	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:18

S95	3	S90 and mechanical adj connector and ground adj plane and via and metallized adj polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 14:19
S96	3	"20060094296"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 16:23
S97	9	"6712544"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 16:30
S98	3	("6712544").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/10 16:31
S99	20	("2447299" | "3316798" | "3413886" | "3468091" | "4367053" | "5288191" | "5419650" | "5895189" | "6071036" | "6487882").PN. OR ("6712544").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/10 16:35
S100	14110	@ad<="20050429" and ("PCB" or "printed circuit board" or substrate) with chip same pad and ground adj layer and insulativeand passive and grooves	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 18:13
S101	30	174/661.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/10 18:13
S102	175	"5353498"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:27
S103	2	("5353498").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/11 09:28
S104	54	packaging adj substrate and array and chip adj pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:38

S105	54	S104 and chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:39
S106	6925353	S105 and via window open$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:39
S107	36	S105 and via	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:40
S109	1	S104 and overflow near preventive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:41
S111	14040	chip near pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:42
S112	54	packaging adj substrate and array and chip adj pad and S111	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:42
S113	77	packaging adj substrate and chip adj pad and S111	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:42
S114	2	S113 and overflow near preventive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:42
S115	2	"overflow-preventive grooves "	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:53
S116	4	"overflow-preventive"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:55
S117	48	"2763403"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 09:56

S119	118	packaging adj substrate and chip near pad	USPAT	OR	ON	2008/04/11 10:01
S120	311451	packaging adj substrate and chip near pad and overflownear grooves	USPAT	OR	ON	2008/04/11 10:01
S124	8	packaging adj substrate and chip near pad and grooves	USPAT	OR	ON	2008/04/11 10:02
S125	4	"overflow-preventive"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 10:04
S126	198522	"overflow"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 10:04
S127	1	S104 and S126	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 10:05
S128	50	S126 and array and chip adj pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 10:05
S129	5	S128 and grooves	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 10:06
S130	272	@ad<= "20040924" and ("PCB" or "printed circuit board") with insulating adj substrate and capacitor and insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 11:34
S131	85	S130 and conductive adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 11:35
S132	9758	S131 conductive adj circuit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 11:36
S134	1	S131 and conductive near circuit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 11:36

S135	64	@ad<="20040924" and ("PCB" or "printed circuit board") with insulating adj substrate and capacitor and insulating adj substrate and resistors and capacitors and conductive adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 11:53
S136	52	S135 and integrated adj circuit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 11:54
S137	21	S136 and electrodes and capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/11 11:54
S138	8	"6,948,940"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/14 10:31
S139	2	("6,948,940").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/14 10:31
S140	2	("11116066").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/14 10:48
S141	3	"11116066"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/14 10:49
S142	8	"6948940"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/14 11:10
S143	2	("6948940").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/14 11:10
S144	1317	174/254.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/01 10:48

S145	7	"6,262,473"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/01 10:49
S146	1319	174/254.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 04:40
S147	49	"4814855"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 04:43
S148	2	("4814855").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 04:43
S149	2	("5859471").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 04:44
S150	147	("4707724" | "5311056").PN. OR ("5859471").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 04:46
S151	21	"5357400"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 04:50
S152	2	("5357400").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 04:50
S153	2	("6992372").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 04:51
S154	3	("6320135").PN. OR ("6992372").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 04:52
S155	1	"10519144"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 05:02
S156	12	"6320135"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 05:07
S157	2	("6320135").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 05:08

S158	2	("20050056915").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 05:19
S159	1	("2005/0056915").URPN.	USPAT	OR	ON	2008/12/05 05:20
S160	6	("20050056915" | "20050121779" | "20050186702" | "20050194693" | "20060103027" | "6992372").PN. OR ("7282389").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 05:20
S161	6	"6,262,473"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:23
S162	2	("6,262,473").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 06:23
S163	1	("6320135").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:32
S164	7	("4177519" | "5338973" | "5585675" | "5820952" | "5996768" | "6180215" | "6201194").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:33
S165	1315	174/250.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:33
S166	5	S165 and dummy adj wiring	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:34
S167	18	sprocket adj holes and dummy adj wiring	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:35
S168	2	S165 and S167	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:35
S169	1	"20040004823"	USPAT	OR	ON	2008/12/05 06:38
S170	13	"6572780"	USPAT	OR	ON	2008/12/05 06:42
S171	2	("6572780").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 06:42
S172	21	sprocket adj holes and dummy adj near2 wiring	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:44
S173	5369	sprocket adj holes	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:44
S174	589	dummy adj wiring	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:45
S175	18	S173 and S174	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:45

S176	2	("20010045651" | "20030020163").PN. OR ("6958288").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:48
S177	1	"20040238968"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 06:51
S178	2	"20040004823"	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 07:28
S179	310	sprocket adj holes and concave	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 08:24
S180	194322	("printed circuit board" or "PCB")	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 08:25
S181	12	S179 and S180	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 08:25
S182	1003	361/749.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 08:41
S183	2	S182 and sprocket adj holes and dummy adj wiring	US-PGPUB; USPAT; USOCR	OR	ON	2008/12/05 08:43
S184	5	"5361490"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 08:58
S185	2	("5361490").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 08:59
S186	2	("5,796,570").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 09:26
S187	2	("20030071349").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 11:36
S188	2	("2002176989").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 11:43
S189	2	"20020176989"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:54
S190	3	"11230336"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:14

S191	2	("11230336").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/05 12:14
S192	0	("2006/0109635").URPN.	USPAT	OR	ON	2008/12/05 12:19
S193	218124	@ad<="20040415" and ("PCB" or "printed circuit board") with shield and ground adj layer and electromagnetic adj radiation and via metal adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/11 19:36
S194	160	S193 and 174/254.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/11 19:39
S195	36	("3179904" | "3201767" | "3221286" | "3459879").PN. OR ("3579206").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/11 19:50
S197	97	S193 and housing with gap and shielding	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/11 19:55
S198	788	361/88.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/11 20:02
S202	376	(("PCB") or ("printed circuit board")) with insulating adj substrate and capacitor and insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/11 20:15
S203	42	chip and film near carrier near film and insulating adj substrate and capacitor and insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/11 20:22
S204	2	"7255919"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/12 08:54

S205	32	("20030038379" | "20030091842" | "20030145949" | "20050205972" | "3503782" | "3554835" | "5073422" | "5082706" | "5273805" | "5281455" | "5759455" | "5965226" | "6210767" | "6280831" | "6280851" | "6320135" | "6441474" | "6458234" | "6476330" | "6521309" | "6548234" | "6572780" | "6605369" | "6613987" | "6617521" | "6624520" | "6761948" | "6794031" | "6900989" | "6911729").PN. OR ("7255919").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/12 08:55
S206	2	"US 20040212050"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2009/04/20 14:21
S207	13	"6559524"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:27
S208	2	("6559524").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/20 14:27
S209	2	"US 20060054349"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2009/04/20 14:28
S211	2	("20010054754").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/20 14:47
S214	28	"4341594"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:49
S215	2	("4341594").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/20 14:50
S216	2	("6559529").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/20 14:51

S217	2	"20030038379"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:52
S218	2	("5615477").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/20 15:02
S219	4	("2003/0038379").URPN.	USPAT	OR	ON	2009/04/20 15:04
S220	2	("6900989").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/20 15:09
S221	3	"US 20050167818"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2009/04/20 15:10
S223	13	"5281455"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:11
S224	2	("5281455").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/20 15:11
S225	2	("5073422").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/20 15:12
S226	4	("3554835").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/20 15:12
S227	4	("3503782").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/20 15:12
S228	28	"3503782"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:12
S229	14	"6572780"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:13

S230	2	("6572780").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/20 15:13

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